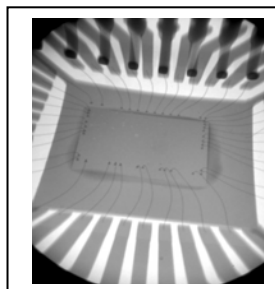
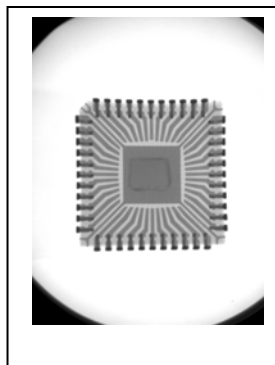
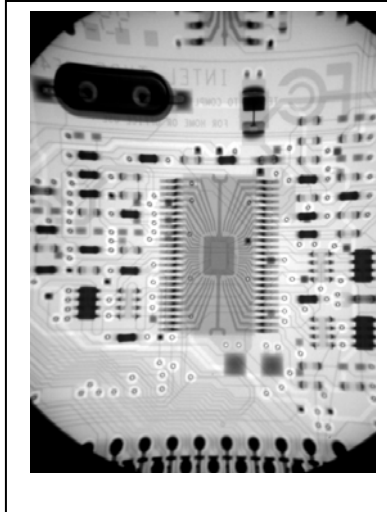
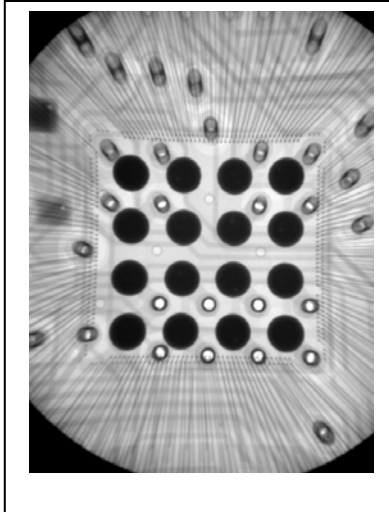


# *Real Time X-Ray (RTX) Non-destructive Defect Analysis*



Real Time X-Ray is a non-destructive inspection technique for wire bond inspection, die surface to package delamination; BGA and Flip Chip solder ball integrity and printed circuit boards. Real Time sample tilt, rotation and manipulation provide a fast low cost method for identifying package related defects or as an initial means to eliminate package related defects prior to a comprehensive Failure Analysis. Nanolab offers a 160kV capability that can penetrate heat sinks or dense packaging materials with a one micron spot size that provides high quality imaging for small defect detection.

For information or to arrange a demonstration please contact the New Pioneers in Failure Analysis:

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